



TECHNICAL DATA SHEET

KEIM TEC-PLATTE

1. PRODUCT DESCRIPTION

Steam-cured, hydrophobic fibre cement board. : Z-31.4-160

2. FIELD OF APPLICATION

Approved for use as load-bearing and stiffening cladding of timber components in accordance with DIN 1052/ Eurocode 5 as per Z-31.4-160.

Facade areas subject to impact hazards:

For ETICS facades e.g. base and ground floor areas in residential complexes, schools, kindergartens.

Bridging of substrates that are not suitable for bonding:

Plaster base board for bridging substrates that are not suitable for bonding in ETICS areas. Standard detail: Bridging area 20 cm. 2/3 of the KEIM TEC board must be fully bonded to the mineral substrate and additionally dowelled with suitable collar dowels, e.g. NDK (detail 5.2.3).

Bridging of external Venetian blind/roller shutter boxes:

For bridging external Venetian blinds or roller shutter boxes, the TEC boards must be bonded exclusively to the insulation material and dowelled using ejothem STR U 2G as described below. The TEC panels project 30 cm into the insulation surface at the sides and 2/3 (1/3 = external Venetian blind height) above. Maximum length of Venetian blinds: 2.40 m, double-layer installation may be required. For spans over 6.0 m, expansion joints must be planned.

3. PRODUCT PROPERTIES

- for interior and exterior use
- Increases the pressure and impact resistance of the system
- fire behaviour: non-flammable, Class A2-s1,d0 according to EN 13501-1
- Use category I according to ETAG 004
- fiber-reinforced
- form- and pressure-stable
- mineral
- resistant to aging
- alkali-resistant
- frost-resistant

MATERIAL CHARACTERISTICS:

- | | |
|--------------------|----------------|
| - Panel size: | 1200 x 1250 mm |
| - Panel thickness: | 10 mm |
| - Edge formation: | square |
| - Colour shade: | light grey |

4. APPLICATION INSTRUCTIONS

SUBSTRATE PREPARATION:

The substrate must be strong, dry, clean, sound and free from adhesion-reducing residues. Unevenness of up to 1 cm/m may be bridged. Larger unevenness must be mechanically levelled or by applying a render in accordance with DIN EN 998-1.

TECHNICAL DATA SHEET – KEIM TEC-PLATTE

Strongly sanding or unevenly absorbent surfaces should be primed with KEIM Indulaqua primer. Observe the Technical Data Sheet of the primer with regard to execution and dilution.

APPLICATION CONDITIONS:

Ambient and substrate temperature during application and drying from min. 5 °C to max. 30 °C. Do not apply in direct sunlight or on sun-heated substrates. Protect surfaces from direct sun, wind and rain during and after application.

CONSUMPTION:

approx. 1 m²/m²

approx. 5,0 kg/m² Pulverkleber-90 for gluing

GLUING:

The TEC-Platte is tightly butted and bonded in the bond – at the building corners in offset - over the entire surface and additionally dowelled into the wall. The connection joints to adjacent building components, such as windows and doors, are sealed with Iso MembraSX joint sealing tape. Transitions to the insulation surface are double reinforced. KEIM Pulverkleber-90 (powder adhesive) is applied to the full surface of the back of the board with a 10 mm notched trowel. The TEC-Platte is then pushed in and pressed on flush with the surface. Immediately after bonding, the TEC-Platte is dowelled through the insulation material into the load-bearing substrate using building authority-approved screw dowels ejotherm STR-U 2G. First the drill holes are drilled exactly at right angles and then the recesses for the dowel plates are milled into the TEC-Platte with the KEIM TEC milling cutter so that the dowel plate can be installed flush with the surface. After inserting the EPS plugs, the anchor plates are filled with the appropriate reinforcement mortar.

Screwing to solid substrates, e.g. when bridging substrates that are not suitable for bonding according to detail 5.2.3, can be done with commercially available collar dowels, e.g. ejot ND-K.

The TEC-Platte may also be applied in 2 layers offset. For this purpose, the first layer is to be screwed into the substrate, the second layer is to be screwed onto the first layer using commercially available, non-rusting drywall screws (number and pitch according to static requirements).

Special processing instructions for surface-flush installation:

The insulation boards must be 20 mm thicker above the KEIM TEC boards. The joints of the KEIM TEC boards must not be above the joints of the insulation boards. No board joints at the corners of facade openings (e.g. windows).

REINFORCEMENT:

A double reinforcement of at least 50 cm width is inserted at the transition to the insulation material. Then the entire surface is reinforced and plastered. The termination in the edge area of the board, e.g. when spanning over roller shutter boxes, must be made using KEIM TEC profile.

Required field sizes are to be determined object-specifically by the planner in case of large-area application (> 2.5 x 12.0 m).

5. PACKAGING

Panel thickness [mm]	Panel size [mm]	Pieces per unit	m ² per bundle	Type of container
10	1200 x 1250	1	1.5	piece

Other dimensions on request

TECHNICAL DATA SHEET – KEIM TEC-PLATTE

6. STORAGE

Storage conditions
even dry protect from moisture

7. DISPOSAL

Waste code: 17 01 01

8. SAFETY INSTRUCTIONS

No particular indications.

9. GENERAL INFORMATION

The Z-31.4-160 must be observed.

The stated values and properties are the result of extensive development work and practical experience. Our recommendations for application, whether given verbally or in writing, are intended to provide assistance in the selection of our products and do not establish a contractual relationship. In particular, they do not release the purchaser and processor from the obligation to convince themselves of the suitability of our products for the intended application with due care, which is general practice in trade and crafts. The general rules of construction technology must be observed. We reserve the right to make modifications to improve the product or its application. This edition supersedes all earlier editions.

